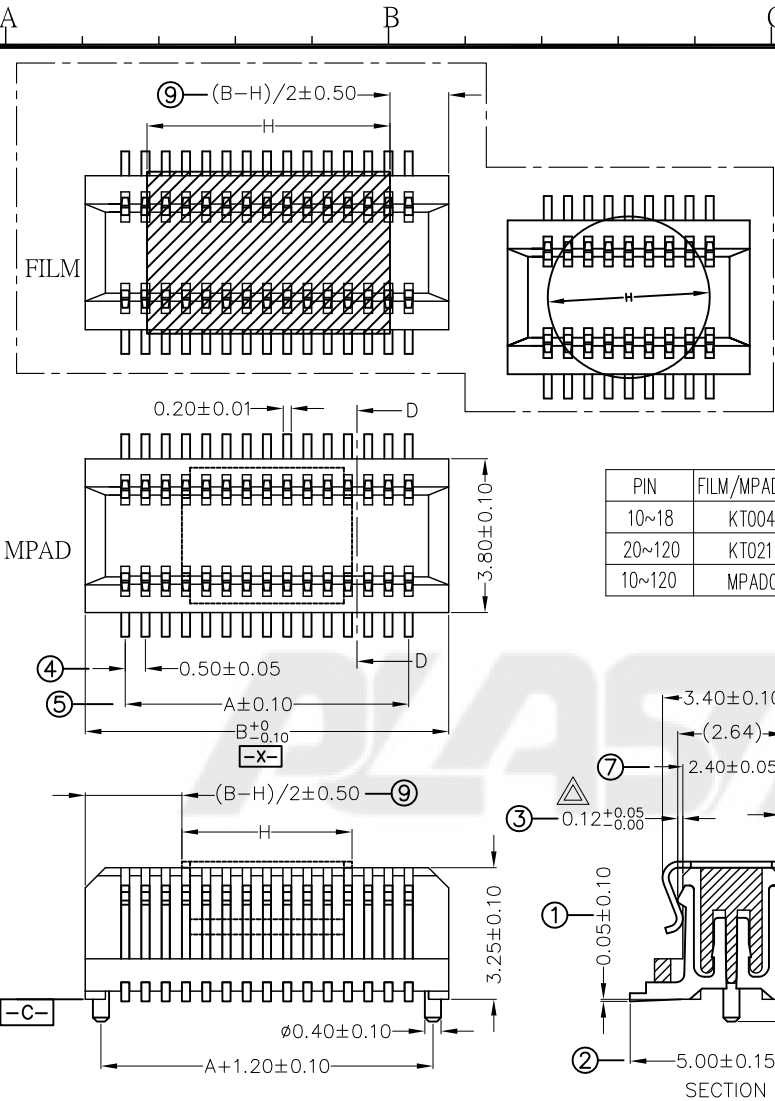


CIRCUITS	DIM A	DIM B	TWN		NHK	
			WITH PEG	W/O PEG	WITH PEG	W/O PEG
10	2.00	3.98	⊙	○	⊕	⊕
12	2.50	4.48	⊙	○	⊕	⊕
14	3.00	4.98	⊙	○	⊕	⊕
16	3.50	5.48	⊙	○	⊕	⊕
18	4.00	5.98	⊙	○	⊕	⊕
20	4.50	6.48	⊙	○	⊕	⊕
22	5.00	6.98	⊙	○	⊕	⊕
24	5.50	7.48	⊙	○	⊕	⊕
26	6.00	7.98	⊙	○	⊕	⊕
28	6.50	8.48	⊙	○	⊕	⊕
30	7.00	8.98	⊙	○	⊕	⊕
32	7.50	9.48	⊙	○	⊕	⊕
34	8.00	9.98	⊙	○	⊕	⊕
36	8.50	10.48	⊙	○	⊕	⊕
38	9.00	10.98	⊙	○	⊕	⊕
40	9.50	11.48	⊙	○	⊕	⊕
42	10.00	11.98	⊙	○	⊕	⊕
44	10.50	12.48	⊙	○	⊕	⊕
46	11.00	12.98	⊙	○	⊕	⊕
48	11.50	13.48	⊙	○	⊕	⊕
50	12.00	13.98	⊙	○	⊕	⊕
52	12.50	14.48	⊙	○	⊕	⊕
54	13.00	14.98	⊙	○	⊕	⊕
56	13.50	15.48	⊙	○	⊕	⊕
58	14.00	15.98	⊙	○	⊕	⊕
60	14.50	16.48	⊙	○	⊕	⊕
62	15.00	16.98	⊙	○	⊕	⊕
64	15.50	17.48	⊙	○	⊕	⊕
66	16.00	17.98	⊙	○	⊕	⊕
68	16.50	18.48	⊙	○	⊕	⊕
70	17.00	18.98	⊙	○	⊕	⊕
72	17.50	19.48	⊙	○	⊕	⊕
74	18.00	19.98	⊙	○	⊕	⊕
76	18.50	20.48	⊙	○	⊕	⊕
78	19.00	20.98	⊙	○	⊕	⊕
80	19.50	21.48	⊙	○	⊕	⊕
82	20.00	21.98	⊙	○	⊕	⊕
84	20.50	22.48	⊙	○	⊕	⊕
86	21.00	22.98	⊙	○	⊕	⊕
88	21.50	23.48	⊙	○	⊕	⊕
90	22.00	23.98	⊙	○	⊕	⊕
92	22.50	24.48	⊙	○	⊕	⊕
94	23.00	24.98	⊙	○	⊕	⊕
96	23.50	25.48	⊙	○	⊕	⊕
98	24.00	25.98	⊙	○	⊕	⊕
100	24.50	26.48	⊙	○	⊕	⊕
110	27.00	28.98	⊙	○	⊕	⊕
120	29.50	31.48	⊙	○	⊕	⊕



PIN	FILM/MPAD P/N	DIM.H
10~18	KT004	ø4.00
20~120	KT021	6.00
10~120	MPAD0014	4.20

- NOTES: (UNLESS OTHERWISE SPECIFIED)
- DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994
 - INSERTION FORCE: 110g MAX. PER CONTACT.
 - WITHDRAW FORCE: 11g MIN. PER CONTACT.
 - DURABILITY: 30 CYCLES MIN..
 - CONTACT RETENTION FORCE: 150g MIN. PER CONTACT.
 - CURRENT RATING: 0.3 AMPERE.
 - CONTACT RESISTANCE: 60 m ohms MAX. FOR INITIAL.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms./MINUTE.
 - INSULATION RESISTANCE: 100 Megohms MIN..
 - DIM. MARKED ①②③SHOULD BE CONTROLLED BY QC
MARKED ▽ SHOULD BE CONTROLLED BY THE CPK
 - HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
 - PRODUCT NUMBER MATRIX:

ZVA-XXS1-X-X-*

NO.OF CONTACT
STRAIGHT

NULL: TUBE(W/O MPAD)
E: MPAD+TUBE
B: MPAD+REEL
K: REEL
C: FILM+REEL
F: FILM+TUBE
0:W/O Locating peg
1:With Locating peg

Contact Plating

Definition	Code
⊙ Tin plated:	A
⊙ Gold plated:	
flash B 15μ" F	
10μ" E 30μ" J	
⊙ Duplex plating:	
flash K 15μ" P	
10μ" N 30μ" U	
⊙ Standard: B	
⊙ Prefix "V" means lead free plating	

Diagram	Molding description
○	mass production & assemble mold
⊙	sample & assemble mold
⊕	mass production & fix mold
⊕	sample & fix mold

FILM	1	KT021/KT004	KAPTON FILM
MPAD	1	MPAD0014	SUS
CONTACT	OP'	B0500285-XX	PHOSPHOR BRONZE, GOLD, TIN OR TIN/LEAD PLATING OVER NICKEL
HOUSING	1	ZVA-XXS1-X	THERMOPLASTIC,UL RATED 94V-0.
PART	Q'TY	P/N	MATERIAL&FINISH

 Plastron Precision Co., Ltd.	GENERAL TOLERANCE		SCALE 1=1	ORIGINAL DRAWN RAY LI	DATE 10.06 '06	DWG. NO. 351-0000-0146	TITLE ASSEMBLY DRAWING	REV. 20
	XX. ± 0.40	XXX. ±	UNIT MM	CHECK Lan Lui	DATE 03.13 '14			PARTS NO.(INTENDED USE) ZVA-XXS1-X-X-*
	X. ± 0.25	.XXX ±	SIZE A4	APPROVE Lan Lui	DATE 03.13 '14	1/1		
	.X ± 0.15	X.° ± 3'						
.XX ± 0.10	.X° ± 3'							